

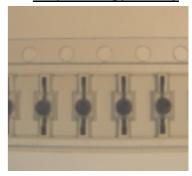
## **Technical Data Sheet**

## 1.9mm Round Subminiature "Z-Bend" Lead Infrared LED

## IR91-21C/TR10

#### **Features**

- Small double-end package
- High reliability
- Low forward voltage
- Good spectral matching to Si photodetector



### **Descriptions**

IR91-21C/TR10 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens. The device is spectrally matched with silicon photodiode and phototransistor.

### **Applications**

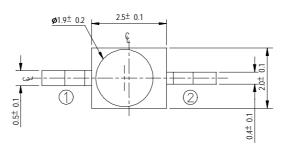
- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

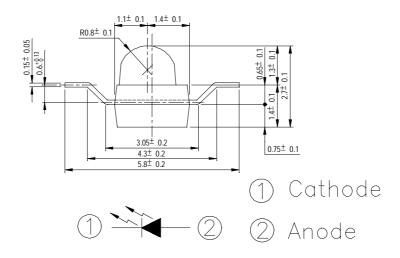
#### **Device Selection Guide**

LEDD AN	Chip		
LED Part No.	Material	Lens Color	
IR	GaAlAs	Water Clear	



# **Package Dimensions**





**Notes:** 1.All dimensions are in millimeters

2. Tolerances unless dimensions  $\pm$  0.1 mm

# Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Continuous Forward Current	$I_{\mathrm{F}}$	65	mA
Peak Forward Current	$I_{FP}$	1.0	A
Reverse Voltage	$V_R$	5	V
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{stg}$	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Soldering Temperature	$T_{sol}$	260	$^{\circ}\!\mathbb{C}$
Power Dissipation at(or below)	$P_d$	130	mW
25°C Free Air Temperature			

**Notes:** \*1: $I_{FP}$  Conditions--Pulse Width  $\leq 100 \mu$  s and Duty  $\leq 1\%$ .

<sup>\*2:</sup>Soldering time ≤ 5 seconds.



## Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Units
Radiant Intensity	E <sub>e</sub>	$I_F=20mA$	3.0	5.0	1	
		$I_F=100mA$	1	25	1	mW/sr
		$I_F=1A$	1	250	1	
Peak Wavelength	λp	$I_F=20mA$	1	940	1	nm
Spectral Bandwidth	Δλ	$I_F=20mA$	1	45	I	nm
Forward Voltage	$V_{\mathrm{F}}$	$I_F=20mA$		1.2	1.5	V
		I <sub>F</sub> =100mA		1.4	1.8	
		$I_F=1A$	-	2.6	4.0	
Reverse Current	$I_R$	$V_R=5V$	1		10	$\mu$ A
View Angle	2 \theta 1/2	$I_F=20mA$		25		deg

**Notes:** \*1:I<sub>F</sub> Conditions--Pulse Width  $\leq$  100  $\mu$  s and Duty  $\leq$  1%.

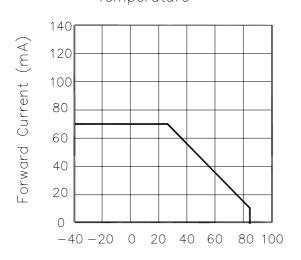
**Intensity Specifications for Bin Grading** 

Rank	<b>Test Condition</b>	Min	Max	Unit
J		3.0	4.5	
K	1	4.0	6.0	
L		5.0	7.5	
M		6.0	9.0	
N	I <sub>F</sub> =20mA	7.0	10.5	****/
P		8.0	12.0	mW/sr
Q		9.0	13.5	
R		10.0	15.0	
S		11.0	16.5	
T		12.0	18.0	



## **Typical Electro-Optical Characteristics Curves**

Fig.1 Forward Current vs. Ambient Temperature



Ambient Temperature (°C)

Fig. 3 Peak Emission Wavelength vs. Ambient Temperature

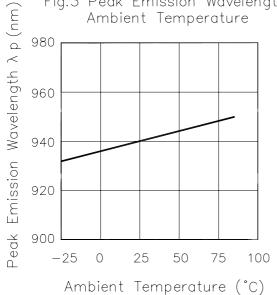


Fig. 2 Spectral Distribution

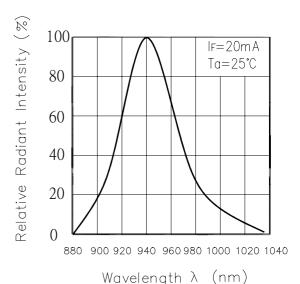
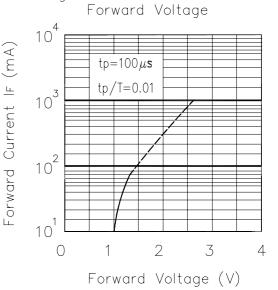


Fig.4 Forward Current vs.





## **Typical Electro-Optical Characteristics Curves**

Fig.5 Relative Intensity vs. Forward Current

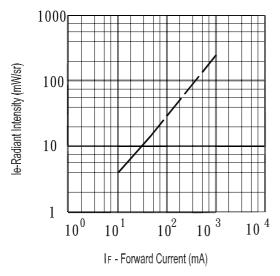


Fig.7 Relative Intensity vs. Ambient Temperature ( ° C)

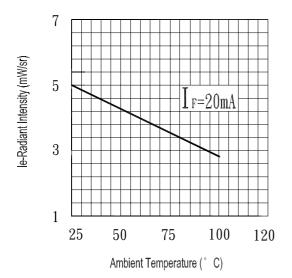


Fig.6 Relative Radiant Intensity vs. Angular Displacement

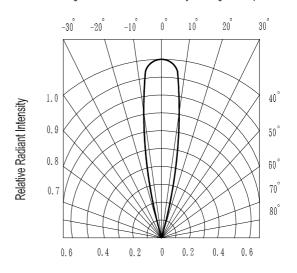
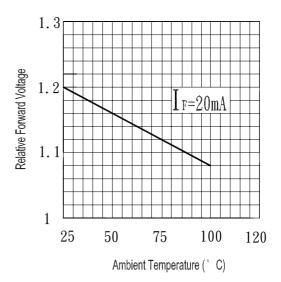
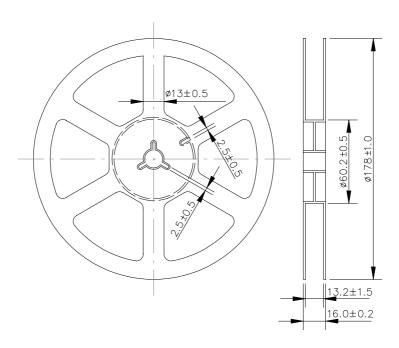


Fig.8 Forward Current vs. Ambient Temperature ( ° C)

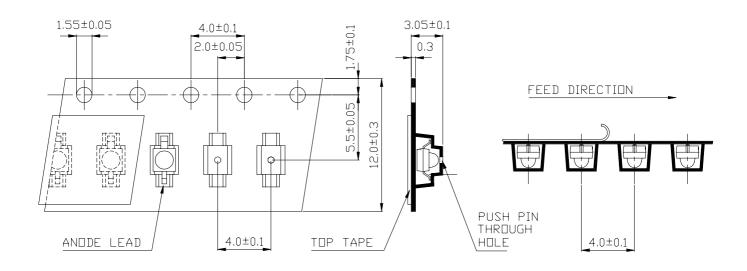




### **Package Dimensions**



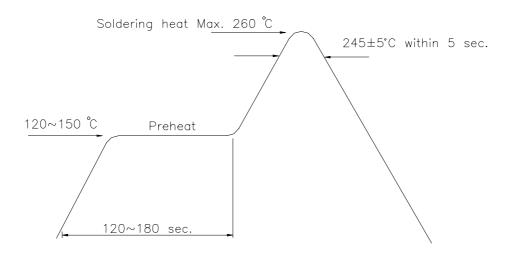
## Loaded Quantity Per Reel 1000PCS/Reel





### Soldering heat reliability(DIP)

Please refer to the following figure



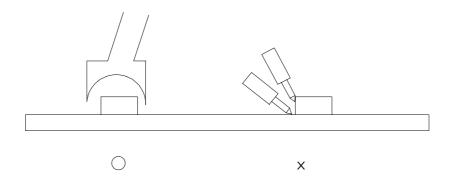
### **Soldering Iron**

Basic spec is  $\leq 5$  sec when 260°C. If temperature is higher, time should be shorter (+10°C)

-1sec). Power dissipation of Iron should be smaller than 15W , and temperature should be controllable. Surface temperature of the device should be under  $230^{\circ}$ C.

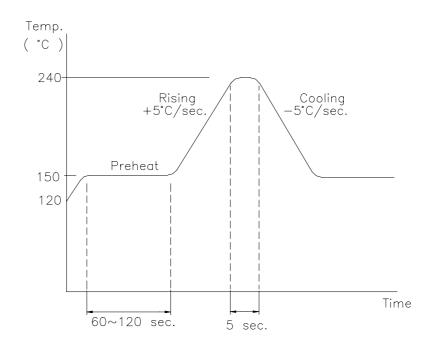
#### Rework

- 1. Customer must finish rework within 5 sec under 245°C.
- 2. The head of iron can not touch copper foil.
- 3.Twin-head type is preferred.





### Reflow Temp./Time



#### **Precautions For Use**

#### 1.Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change(Burn out will happen).

#### 2.Storage

- 2.1 The operation of temperature and R.H are  $:5^{\circ}\text{C} \sim 35^{\circ}\text{C}$ , R.H.60%.
- 2.2 Once the package is opened, the products be should be used within a week. Otherwise, they should be keep in a damp proof box with desiccating anent. Considering the tape life, we suggest our customers to use our products within a year (from production date).
- 2.3 If opened more than one week in an atmosphere  $5^{\circ}\text{C} \sim 35^{\circ}\text{C}$ , R.H.60%. , they should be treated at  $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 15hrs.
- 2.4 When you discover that the desiccant in the package has a pink color(normal=blue), you should treat them in the same conditions as 2.3



### **Reliability Test Item And Condition**

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

NO.	Item	Test Conditions	Test Hours/	Sample	Failure	Ac/Re
			Cycles	Sizes	Judgement	
					Criteria	
1	REFLOW	TEMP. : 240°C± 5°C	6mins	22pcs	More than	0/1
		5secs			90% of lead	
					to be covered	
					by soldering	
2	Temperature Cycle	H : +85°C 30mins	50Cycle	22pcs		0/1
		5mins		1	$I_R \geqq U \times 2$	
		L:-55°C <b>3</b> 0mins			Ee≦Lx 0.8	
3	Thermal Shock	H :+100°C ▲ 5mins	50Cycle	22pcs	$V_F \ge Ux 1.2$	0/1
		▼ 10secs				
		L :-10°C 5mins			U: Upper	
4	High Temperature	TEMP. : +100°C	1000hrs	22pcs	Specification	0/1
	Storage				Limit	
5	Low Temperature	TEMP. : -55°C	1000hrs	22pcs	L: Lower	0/1
	Storage				Specification	
6	DC Operating Life	I <sub>F</sub> =20mA	1000hrs	22pcs	Limit	0/1
7	High Temperature/	85°C / 85% R.H	1000hrs	22pcs		0/1
	High Humidity					

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